

HZD6.8Z4

Silicon Planar Zener Diode for Surge Absorb

REJ03G0201-0200 Rev.2.00 Oct 20, 2004

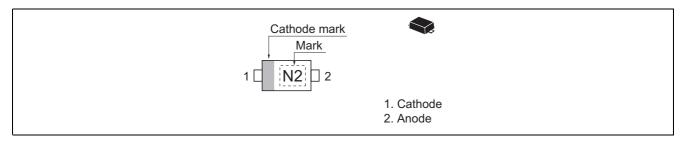
Features

- Low capacitance (C = 4.0 pF max) and can protect ESD of signal line.
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HZD6.8Z4	N2	SFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Power dissipation	Pd *	150	mW
Junction temperature	Тј	150	°C
Storage temperature	Tstg	−55 to +150	°C

Note: See Fig.2.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	6.47	_	7.00	V	$I_Z = 5$ mA, 40 ms pulse
Reverse current	I _R	_	_	2	μΑ	V _R = 3.5 V
Capacitance	С	_	_	4	pF	V _R = 1 V, f = 1 MHz
Dynamic resistance	r _d	_	_	30	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *1*2	_	8	_	_	kV	$C = 150 \text{ pF}, R = 330 \Omega$, Both forward
						and reverse direction 10 pulse

Notes: 1. Failure criterion ; $I_R > 2 \mu A$ at $V_R = 3.5 V$.

- 2. Between cathode and anode.
- 3. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

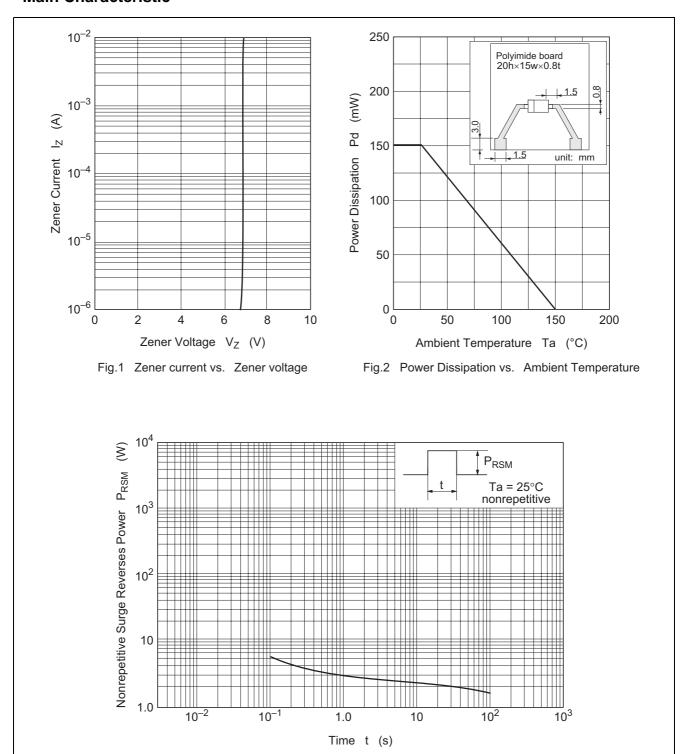
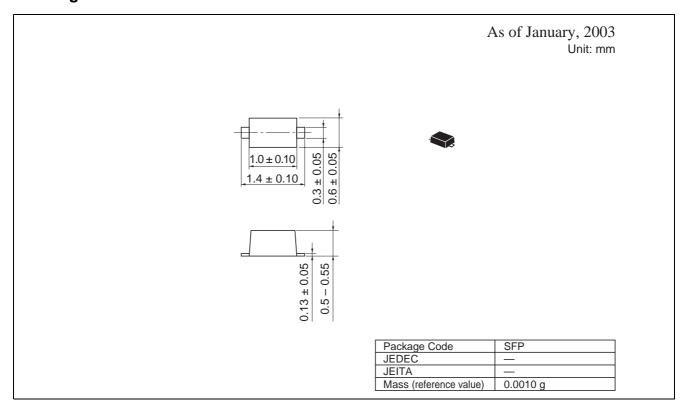


Fig.3 Surge Reverse Power Ratings

Package Dimensions



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